

Title (en)
Epoxy resin composition

Title (de)
Epoxidharzzusammensetzung

Title (fr)
Composition de résines époxydes

Publication
EP 0957122 A3 20020703 (EN)

Application
EP 99109640 A 19990514

Priority
JP 13345098 A 19980515

Abstract (en)
[origin: EP0957122A2] An epoxy resin composition comprising (1) an epoxy resin, (2) a polymer obtained by reacting a polycarbodiimide with a compound having, in the molecule, at least one group reactive with carbodiimide group, between the carbodiimide group of said polycarbodiimide and the group reactive with carbodiimide group, of said compound, and (3) a curing agent for epoxy resin. The above epoxy resin composition alleviates the problems of the prior art; has a long pot life in a solution state, has an appropriate gelling time and accordingly good workability, is superior in film formability and handleability in B-stage, and has high heat resistance after curing; therefore, is suitably used in printed wiring board, prepreg, etc.

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H05K 3/46; C08G 59/40; C08G 18/09; C08L 63/00; C08L 79/00

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C08G 18/09 (2006.01); **H05K 1/03** (2006.01)

CPC (source: EP US)
C08G 18/095 (2013.01 - EP US); **H05K 1/0346** (2013.01 - EP US)

Citation (search report)

- [X] US 5576398 A 19961119 - TAKAHASHI MASAYUKI [JP], et al
- [X] EP 0306451 A2 19890308 - CIBA GEIGY AG [CH]
- [X] PATENT ABSTRACTS OF JAPAN vol. 1998, no. 01 30 January 1998 (1998-01-30)
- [PX] PATENT ABSTRACTS OF JAPAN vol. 1999, no. 09 30 July 1999 (1999-07-30)

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EP0989788A3; EP1108532A1; CN109983403A; US11402754B2; WO2011090668A3

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